

**Amendments to the Specification:**

*Please replace paragraph [0033] of the published application (Pub. No. 2003/0011851) with the following paragraph:*

[0033] FIG. 3 shows a portion 300 of a two dimensional array of lasers 302 created according to the principles of the invention. The portion shows two individual laser devices 302 bonded via contact pads 304 to an electronic chip 306. As shown, the devices 302 are bottom emitting laser devices that have been flip chipped bonded to the electronic chip, although as will be apparent from the description herein, bottom receiving, top emitting or top receiving devices can be used as well, particularly if the approaches of the commonly assigned U.S. patent applications entitled “Opto-Electronic Device Integration,” filed concurrently herewith (now U.S. Patent Nos. 6,620,642, 6,724,794, 6,753,197, and 6,790,691 which are incorporated herein by reference), [[is]] are employed as part of the process.

*Please replace paragraph [0035] of the published application (Pub. No. 2003/0011851) with the following paragraph:*

[0035] During device creation the lasers are separated into individual devices by patterning the laser wafer prior to bonding with the electronic chip, for example as shown in the incorporated commonly assigned application entitled~~[[,]]~~ “Opto-Electronic Device Integration,” now U.S. Patent No. 6,620,642. Additionally, the devices are patterned with grouping trenches 312 which physically and electrically define groups by creating boundaries separating individual groups 314 of redundant devices. The grouping trenches 312 ensure isolation among the individual groups while allowing for carrier movement among the devices within the group via the electrically conductive substrate 308.